PRODUCT CHANGE NOTICE

Alternate Manufacturing Site for the Listed Intersil TQFN Packaged Products

Refer to:
PCN10099

Date: November 3, 2010

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To: Our Valued Intersil Customer

Subject: **Alternate Manufacturing Site for the Listed Intersil TQFN Packaged Products –** *STATS ChipPAC Malaysia*

This notice is to inform you that Intersil is using the STATS ChipPAC Malaysia (SCM) facility as an alternate site for performing assembly, final electrical test, tape and reel, packing, and shipping of the listed TQFN (Thin Quad Flat No Lead) packaged products. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. The site-specific and product verification activities are complete.

The STATS ChipPAC Malaysia (SCM) facility is ISO 9001:2000 and ISO/TS 16949:2009 certified and currently qualified as a primary supplier to Intersil for assembly and testing of QFN/TQFN packaged products. The following summarizes the activities that were conducted prior to production release to confirm there is no impact to form, fit, function, or interchangeability of the product.

- Intersil supplied test software and product specific hardware is used at SCM.
- The test equipment correlation plan involves the testing of golden (control) units and a correlation lot of select products at SCM and the current site.
    - Correlation units were tested, their performance recorded, and the results analyzed to validate the set-up.
    - A correlation lot of approximately 1000 units were tested at the current site and retested at SCM. The test results from each site were compared.
    - Continuous monitoring and comparison of the data from lots processed at multiple sites are an ongoing function of the responsible product engineers.
- The visual/mechanical inspection and tape and reel operations are compliant to JEDEC industry standards used by all Intersil subcontractors.
- The assembly qualification activity is considered QBE (Qualified by Extension) as the existing processes, materials, and equipment used to assemble the current TQFN products at SCM will be used for these products going forward. There will be no change in the package outline drawing (POD). Products assembled at SCM are classified as moisture sensitivity level three (MSL 3 at 260°C per J-STD-020D). The qualified material set combinations are as follows:

Material	Current	SCM
Mold Compound	Sumitomo EME-G770H	Sumitomo EME-G770
Die Attach	Hysol QMI 519	Ablebond 8290

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at SCM may also be identified by the assembly site code (country of assembly) when marked on the devices. The assembly site code for the SCM facility is "H".

Products affected:

ISL6265AHRTZ **	ISL62883HRTZ-T **
ISL6265AHRTZ-T **	ISL62883HRTZ-TS2568 **
ISL62882HRTZ **	ISL62883HRTZ-TS2705 **
ISL62882HRTZR5390 **	ISL62883IRTZ **
ISL62882HRTZ-T **	ISL62883IRTZ-T **
ISL62882HRTZ-TR5390 **	ISL9522HRTZ
ISL62882IRTZ **	ISL9522HRTZ-T
ISL62882IRTZ-T **	ISL9523HRTZ
ISL62883HRTZ **	ISL9523HRTZ-T

** SCM is an existing site approved for package test activities.

Intersil will take all necessary actions to conform to customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product manufactured at either the current or the newly qualified sites beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

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